

Predictive simulation of RF MEMS Jayathi Murthy Purdue University

ASC 2010 PI Meeting February 8-10, 2010 Las Vegas, NV

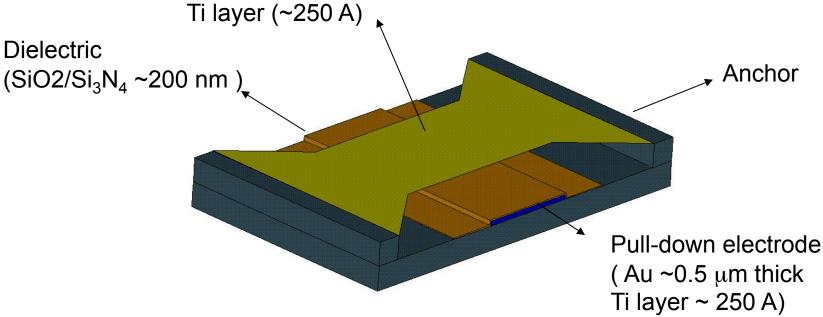






Target PRISM Device

Ni membrane (~1-3 μ m thick)



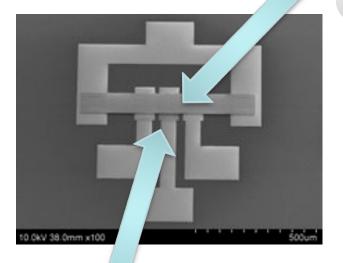
- Contacting capacitive RF MEMS switch
- Used for contact actuators and capacitive switches
- Metal membrane makes periodic contact with thin dielectric layer

- Membrane
 - Length ~ 400 μm
 - Width ~ 100 μm
 - Thickness ~ 1-3 μm
- N₂ or air environment (~ 1 atm)
- Actuation voltage ~ 40-100V
- Hold down voltage ~ 5-15V
- Switching frequency 100 Hz-10 kHz
- Response time 3-10 microseconds



Failure Mechanisms

Fluid damping
Slip and rarefaction effects
Periodic transition between continuum
and rarefied regimes



Creep

Microstructure and size effects, Grain boundaries and free surfaces Dislocation and grain sliding

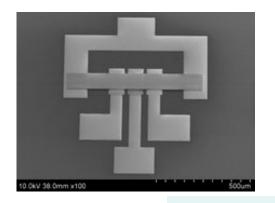
Dielectric charging
Trapped charges,
coupled to defect generation
and evolution

Contact physics
Interactions between surfaces, stiction
Sub-surface defects, surface chemistry



Connection between Scales

Device scale



Full device simulation

C Full device simulation

Full device simulation

 Parameters in dielectric charging model

Phase field micromechanics

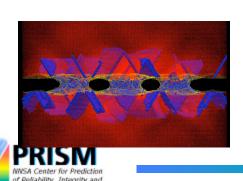
- Capture individual disloca
- •Size effects emerge natu

Electron trapping

III-Si/V-Si

dielectric

Atomistic scale



Atomistic simulations

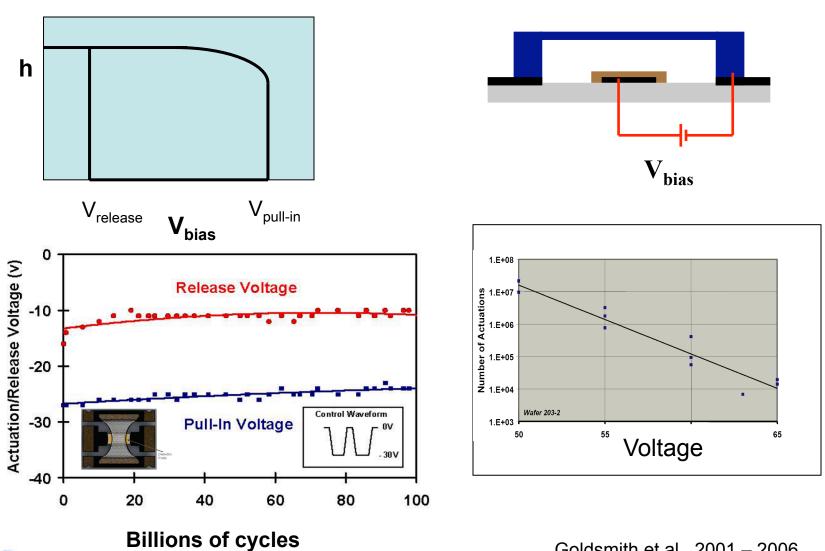
 Properties of individual disloc Atomistic simula

•Pull-out force as a function of ntact

Atomistic simulations

Energy levels of traps

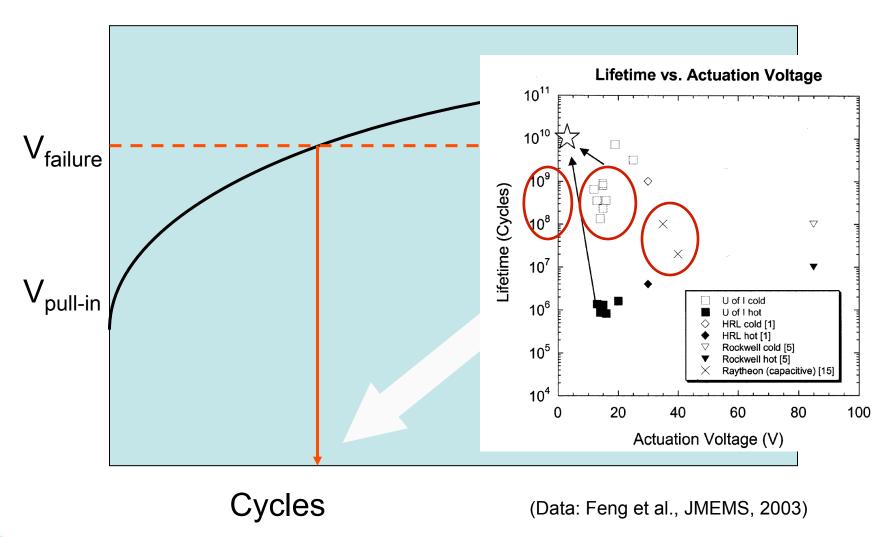
Prediction Goal I – Lifetime Prediction under **Accelerated Testing**





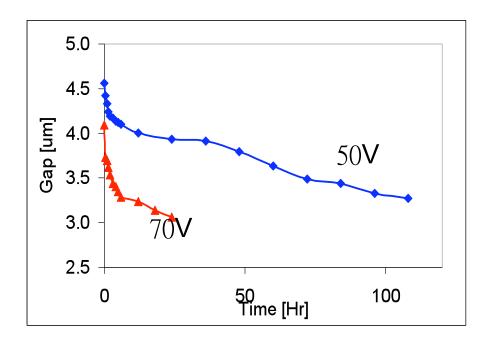
Goldsmith et al., 2001 - 2006

Prediction Goal - I





Prediction Goal -II

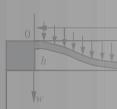


- Predict the change of gap with respect to time at fixed voltage, V_{hold}
- Combination of creep and dielectric charging
- Our goal is to predict critical slopes in the time-evolution of gap to with 20% mean square error with respect to experiment.



V&V a

Coarse-0

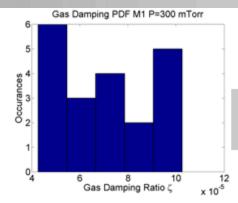


$$\rho_l \frac{\partial^2 w}{\partial t^2} = -\frac{1}{1-\frac{1}{2}}$$

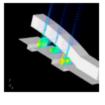
- •2D membra
- •Electrostatio
- ·Fluid dampi
- Contact and
- ·Dielectric ch

Propagate u determine m





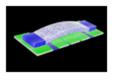
Experimental outputs

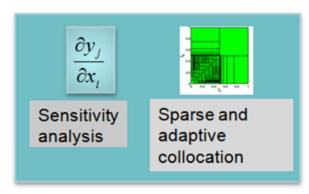


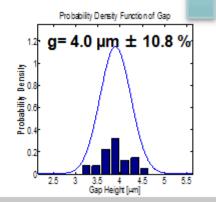
Stochastic Collocation Methods
Generalized Polynomial Chaos (gPC)

Solver
Choice of inputs
from collocation

Epistemic uncertainties in outer loop



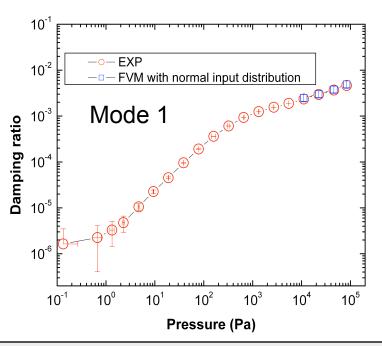




Uncertainty
Quantification
for System
Simulations

Experimental inputs

Uncertainty in Damping Factor: Free Cantilever



Pressure (Pa)	Mean Damping Coeff	Standard Deviation
1.11E+04	0.0025	0.00046768
2.25E+04	0.003	0.000533385
4.59E+04	0.0038	0.000670322
8.36E+04	0.0049	0.000893391



Inputs	PDF
Gas density	unif. & normal
Cantilever thickness t	unif. & normal
Cantilever width b	unif. & normal
Cantilever length L	unif. & normal
Frequency	unif. & normal

Ranges

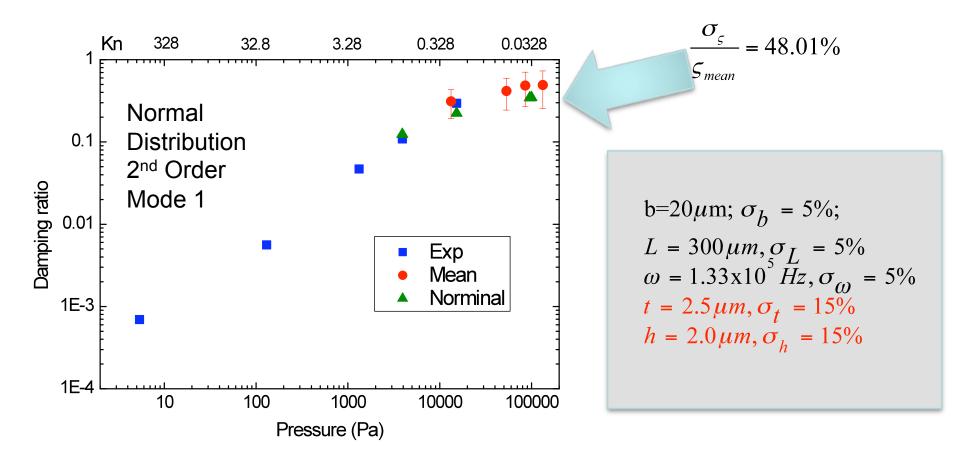
b=35 μ m; $\sigma_b = 5\%$; t = 1 $\rho_g = 0.9707 kg / m^3$ $L = 100 \mu m$, $\sigma_L = 5\%$ $\omega = 1.33 \times 10^5 Hz$, $\sigma_{\omega} = 1.33 \times 10^5 Hz$

Primary culprit is uncertainty in cantilever thickness

Output PDF

Damping factor

Squeeze Film: Continuum and Slip

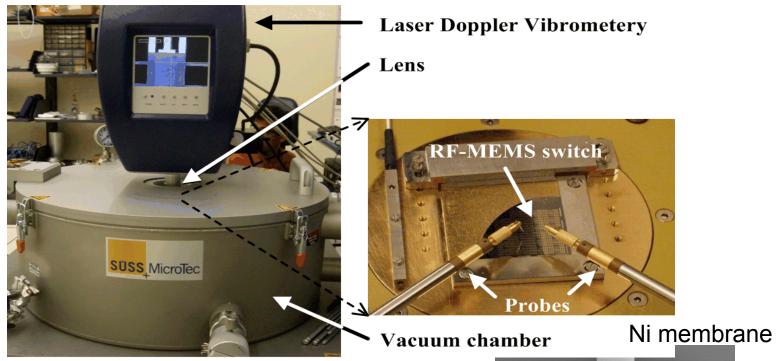




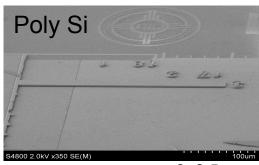
Experimental data from Ozdoganlar et al, Exp. Mech. 45(6), 2005.

Experimental Set-up

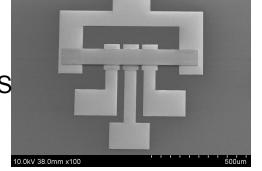
Facility at Purdue's Birck Nanotechnology Center



Squeeze Film Cantilevers



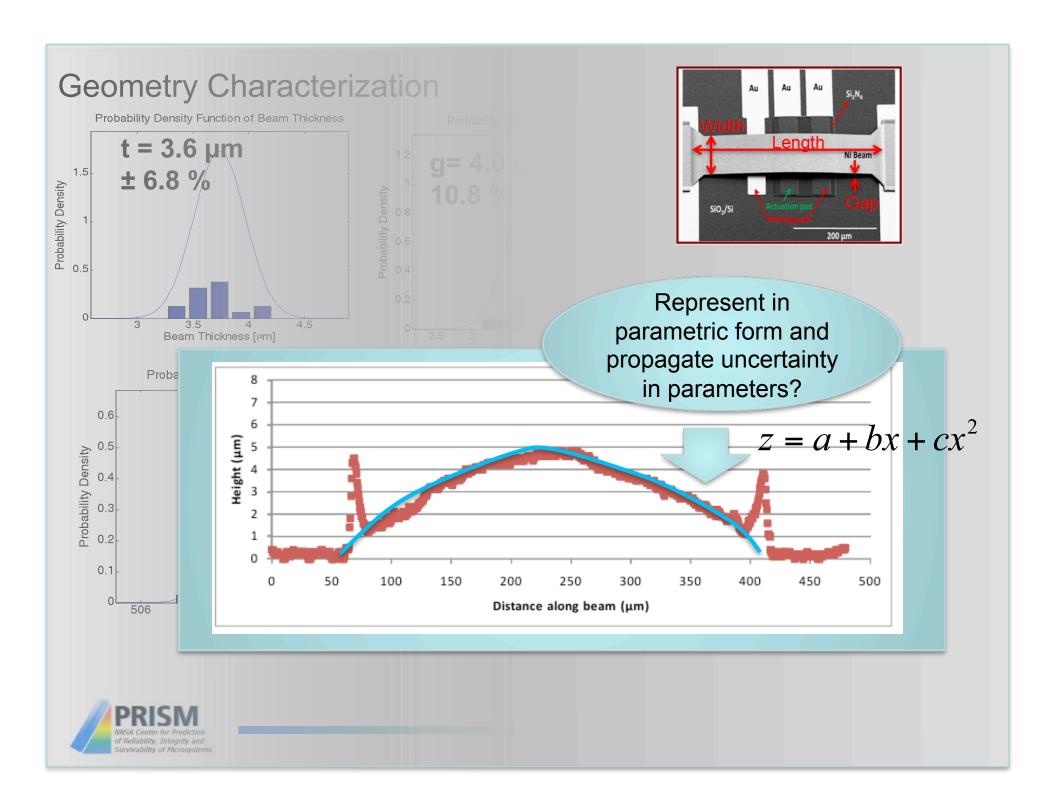
PRISM RF-MEMS



 $l = 200 \ \mu m \ b = 18 \ \mu m \ t_{struc} = 2.25 \ \mu m \ gap = 2.25 \ \mu m$

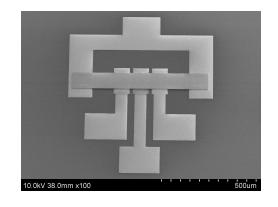


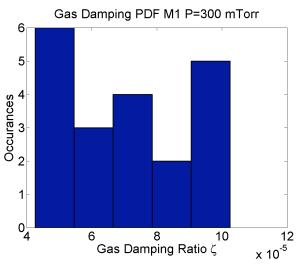
 $l = 400 \ \mu m$ $b = 120 \ \mu m$ $t_{struc} = 3 - 4 \ \mu m$ $gap = 3 - 4 \ \mu m$

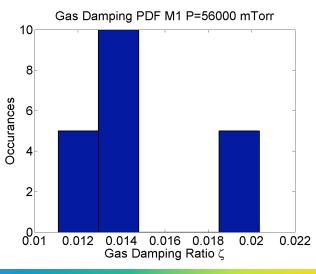


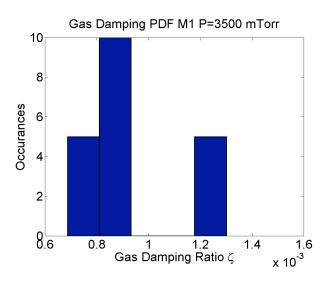
Experimental PDFs of Damping Coefficient

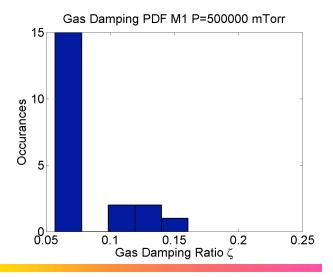
Four devices, five replicates





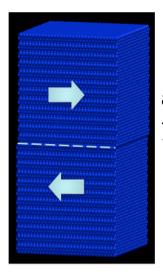




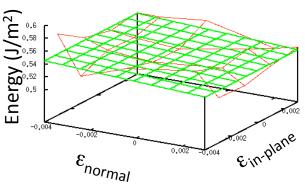




Uncertainty Propagation in Multiscale Simulation

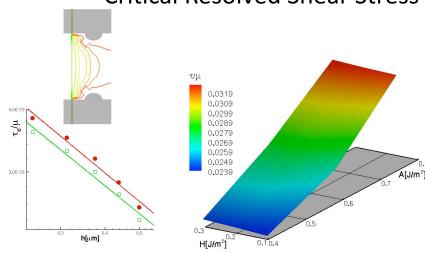


Unstable Stacking Fault Energy

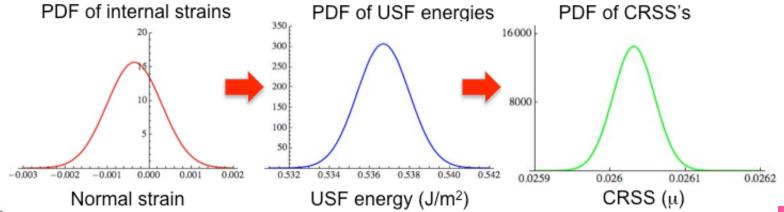


$$A[J/m^2] = 0.536 - 2\varepsilon_{normal} + 0.2\varepsilon_{in-plane}$$

Critical Resolved Shear Stress



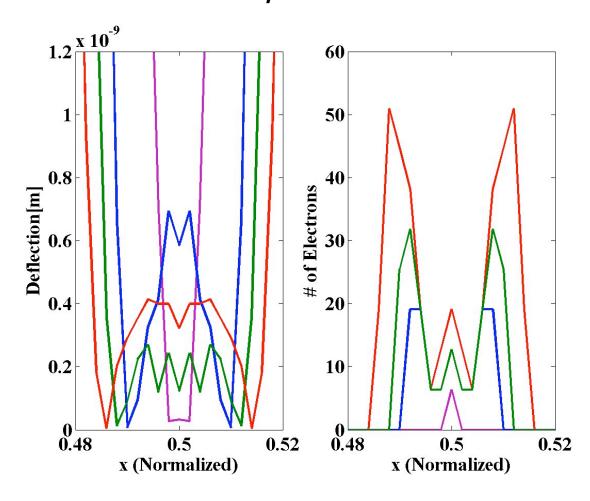
$$\tau_y/\mu = 0.01467 + 0.02117A + 0.003465H$$





Coarse-Grained Model: Membrane Bounce and Charge Injection

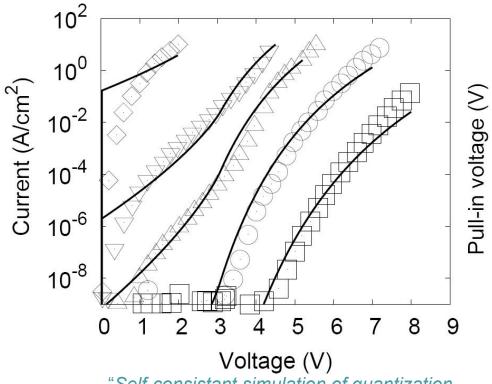
$$\rho_{l} \frac{\partial^{2} w}{\partial t^{2}} = -\frac{EI}{1 - \eta^{2}} \frac{\partial^{4} w}{\partial x^{4}} - b \frac{\partial w}{\partial t} + F_{elec}$$





Dielectric Charging

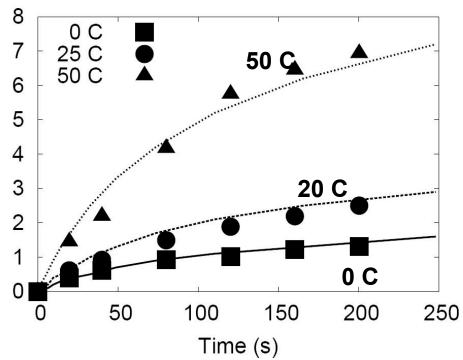
Thickness dependent tunneling current



"Self-consistant simulation of quantization effects and tunneling current in ultra-thin gate oxide MOS devices" – A.Ghetti et. al.



Charge trapping in oxides: theory and experiment



"Temperature acceleration of dielectric charging in RF MEMS capacitive switches"

– Xiaobin Yuan et. al.

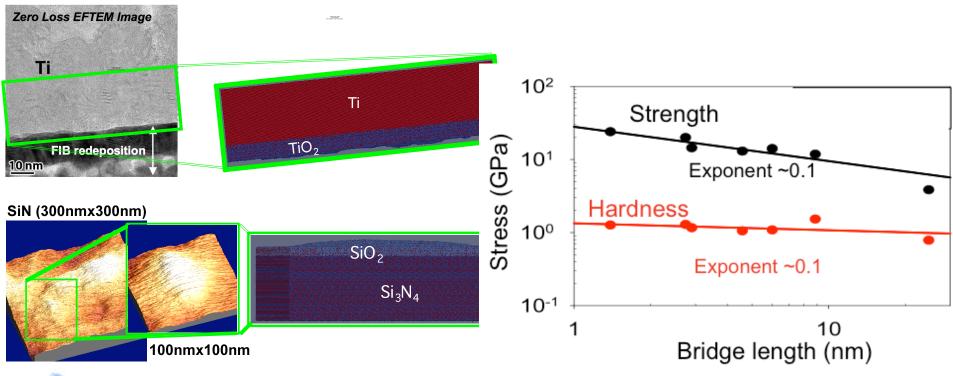


Atomistic Contact Simulations

Goal: For a given surface chemistry & asperity predict:

- •Minimum pull-out force as a function of applied closing force?
- Sub-surface defects are generated in metal and dielectric?

Atomistic models from experimental surface roughness measurements

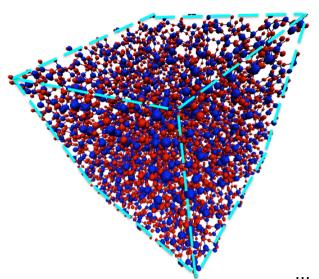




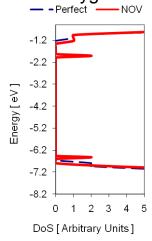
Dielectric Charging: Atomistics

Goal: predict atomic structure and electronic properties of

defects responsible for dielectric charging



Neutral oxygen vacancy

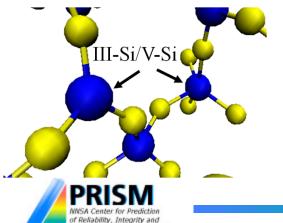


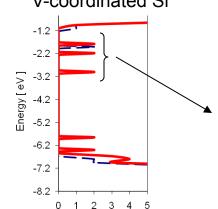
NOV

Approach

MD annealing + DFT relaxation & electronic properties

III-coordinated Si & V-coordinated Si





DoS [Arbitrary Units

Key results

- •Atomistic structure of defects provide insight into defect formation process
- •Electronic levels can trap charge

What We've Learned So Far

- Geometric uncertainty characterization is critical for damping predictions
 - ...and probably for other physics as well
- Uncertainties in input geometry PDFs must be characterized
- Even with low-order cubature and sparse grid approaches, computational cost for UQ is still high
 - Use coarse system-level model to cull variables
 - Explore even simpler (linear?) models, intervals

